

ABSTRACT

A conductive composition for bonding includes a copper powder and a carboxylic acid mixed therewith. The carboxylic acid has a branched carbon chain in its structure. The copper powder comprises first copper particles and second copper particles. The first copper particles have a volume-based cumulative particle size D_{50} of 0.11 μm or more and less than 1 μm at a cumulative volume of 50 vol% in a region of particle sizes of less than 1 μm in a particle size distribution of the copper powder that is determined using a scanning electron microscope. The second copper particles have a volume-based cumulative particle size D_{50} of 1 μm or more and 10 μm or less at a cumulative volume of 50 vol% in a region of particle sizes of 1 μm or more in the particle size distribution of the copper powder that is determined using the scanning electron microscope. The carboxylic acid is contained in an amount of 6 parts by mass or more and 24 parts by mass or less per 100 parts by mass of the copper powder.